

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Hi-Kuk LEE	09/28/2010
Sang-Hyun YUN	09/28/2010
Cha-Dong KIM	09/28/2010
Jung-In PARK	09/28/2010
Deok-Man KANG	10/29/2010
Youn-Suk KIM	10/05/2010
Sae-Tae OH	10/05/2010

**RECEIVING PARTY DATA**

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<b>Street Address:</b>	416, Maetan-Dong, Yeongtong-gu, Gyeonggi-do
<b>City:</b>	Suwon-si
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	443-803

<b>Name:</b>	AZ Electronic Materials K.K.
<b>Street Address:</b>	Bunkyo Green Court, 2-28-8, Honkomagome, Bunkyo-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	113-0021

**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	13037212

**CORRESPONDENCE DATA**

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OP \$40.00 13037212

**501540369**

**PATENT**  
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ATTORNEY DOCKET NUMBER:

P4015US00

NAME OF SUBMITTER:

Hae-Chan Park

**Total Attachments: 8**

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**ASSIGNMENT**

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

an application for United States Letters Patent entitled **PHOTORESIST COMPOSITION AND METHOD OF FORMING PATTERN BY USING THE SAME** ("Application");

upon which United States Letters Patent, Patent Number \_\_\_\_\_, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

(1) **Samsung Electronics Co., Ltd.**

(2) **AZ Electronic Materials K.K.**

416 Maetan-dong, Yeongtong-gu  
Gyeonggi-do  
Suwon-si  
Republic of Korea

Bunkyo Green Court, 2-28-8,  
Honkomagome  
Bunkyo-ku  
Tokyo 113-0021  
Japan

**Samsung Electronics Co., Ltd. & AZ Electronic Materials K.K.**, herein further referred to as ("Assignees").

Now, for valuable consideration by Assignees to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignees and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignees all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement, or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignees will, upon Assignees' request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application, and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation, or proceeding related thereto and will promptly execute and deliver to Assignees or Assignees' legal representative any and all papers, instruments, or affidavits required to apply for, protect, obtain, maintain, issue, defend, and



enforce the Application, Patent, Invention, whether in the US or any and all foreign countries, and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignees thereof shall hereafter require and prepare at Assignees' expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: HI-Kuk LEE

Address: #747-1, Daedae-ri, Yangji-myeon  
Cheoin-gu, Gyeonggi-do  
Yongin-si  
Republic of Korea

First Inventor's Signature: *Hi-Kuk Lee*

Date: *28. 09. 2010*

Second Inventor's Name: Sang-Hyun YUN

Address: #972-11, Ingye-dong, Paldal-gu  
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Suwon-si  
Republic of Korea

Second Inventor's Signature: *Sang Hyun Yun*

Date: *28. 09. 2010*

91732477

Third Inventor's Name: Cha-Dong KIM

Address: 408 Sitteber, #1274, Seongjeong 2-dong  
Seobuk-gu, Chungcheongnam-do  
Cheonan-si  
Republic of Korea

Third Inventors' Signature: *Cha-Dong Kim*

Date: *28. 09. 2010*



Fourth Inventor's Name: Jung-In PARK

Address: F306, 52-12, Gokbanjeong-dong, Gwonseon-gu  
Gyeonggi-do  
Suwon-si  
Republic of Korea

Fourth Inventor's Signature: Jung In Park

Date: 28. 09. 2010

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Fifth Inventor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

SAMSUNG ELECTRONICS

SIXTH INVENTOR'S NAME: Youn-Suk KIM

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Yongin-si  
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SIXTH INVENTOR'S SIGNATURE: \_\_\_\_\_

Date: \_\_\_\_\_

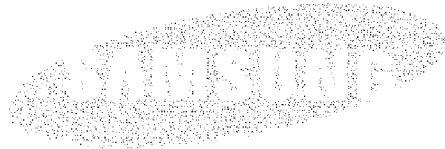


Seventh Inventor's Name: Sae-Tae OH

Address: 101-704 SK Apt., Bijeon-dong, Gyeonggi-do  
Pyeongtaek-si  
Republic of Korea

Seventh Inventor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_



SAMSUNG ELECTRONICS

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- |   |  |
|---|--|
| <p><b>(1) Samsung Electronics Co., Ltd.</b><br/><br/>416 Maetan-dong, Yeongtong-gu<br/>Gyeonggi-do<br/>Suwon-si<br/>Republic of Korea</p> | <p><b>(2) AZ Electronic Materials K.K.</b><br/><br/>Bunkyo Green Court, 2-28-8,<br/>Honkomagome<br/>Bunkyo-ku<br/>Tokyo 113-0021<br/>Japan</p> |
|---|--|

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Assignor hereby covenants that no assignment, sale, agreement, or encumbrance has been or will be made or entered into which would conflict with this Assignment.

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enforce the Application, Patent, Invention, whether in the US or any and all foreign countries, and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignees thereof shall hereafter require and prepare at Assignees' expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Hi-Kuk LEE

Address: #747-1, Daedae-ri, Yangji-myeon  
Cheoin-gu, Gyeonggi-do  
Yongin-si  
Republic of Korea

First Inventor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Second Inventor's Name: Sang-Hyun YUN

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Suwon-si  
Republic of Korea

Second Inventor's Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Third Inventor's Name: Cha-Dong KIM

Address: 408 Sitteber, #1274, Seongjeong 2-dong  
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Cheonan-si  
Republic of Korea

Third Inventors' Signature: \_\_\_\_\_

Date: \_\_\_\_\_





Fourth Inventor's Name: Jung-in PARK

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Yongin-si  
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Sixth Inventor's Signature: *[Signature]*

Date: *Oct. 5th. 2010*



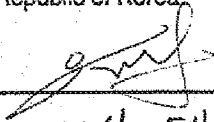
Seventh Inventor's Name:

Sae-Tae OH

Address:

101-704 SK Apt., Bijeon-dong, Gyeonggi-do  
Pyeongtaek-si  
Republic of Korea

Seventh Inventor's Signature:



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Date:

Oct. 5th, 2010